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**MAR 08 2005**

**FAX Transmittal**

**Pages: 9 (including this one)**

**Date: MARCH 2, 2005**

<b>TO:</b>	Office of Petitions
<b>FAX:</b>	(703) 872-9306
<b>FROM:</b>	Steve Gratton
<b>FAX:</b>	(303) 989 6538

**Re: Serial no. 09/266,237  
Docket No. 97-1433**

See attached "Supplement To Petition To Accept Late Payment Of Issue Fee".

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re application of:**

**WARREN M. FARNWORTH  
SALMAN AKRAM**

**Serial No. 09/266,237**

**Art Unit: 2829**

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**Filing Date: 03/10/1999**

**Examiner: KOBERT, R.**

**MAR 08 2005**

**For: TEST INTERCONNECT AND TEST SYSTEM  
FOR BUMPED SEMICONDUCTOR COMPONENTS  
(AS AMENDED)**

**Attorney Docket No. 97-1433**

**SUPPLEMENT TO  
PETITION TO ACCEPT LATE PAYMENT OF ISSUE FEE**

**MARCH 2, 2005**

**Mail Stop Petition  
Commissioner For Patents  
PO Box 1450  
Alexandria, VA 22313-1450**

**Sir:**

Applicant has filed a Petition To Accept Late Payment Of Issue Fee dated October 11, 2004. However, the Petition was defective in that it did not include proof that the Notice of Allowance And Fees Due mailed on 06/08/2004 was not received by the Attorney for Applicant. This Supplement is being filed with proof that the Notice of Allowance And Fees Due was a non received communication.

With respect to proof, MPEP 711.03(c)I.A, requires a statement from the Practitioner that the communication was not received, along with a copy of the docket records for the period for response indicating where the communication

would have been entered had it been received. In view of the foregoing requirements, Attorney for Applicant hereby provides the following statements and documents.

1. Attorney For Applicant did not receive the original "Notice Of Allowance And Fees Due" mailed on 06/08/2004 by the Patent Office.

2. Attorney for Applicant has searched the file jacket and the docket records for docket no. 97-1433 (serial no. 09/266,237). Both the file jacket and the docket records indicate that the above communication was not received.

3. Attached to this Supplement are docket records for "The Law Office Of Steve Gratton" for the period from 06/01/2004 to 10/19/2004, which includes the three month period for response (06/08/2004 to 09/08/2004) for the non received communication.

4. These docket records have been labeled as Exhibits A-D. Exhibit A is dated June 1, 2004. Exhibit B is dated July 21, 2004. Exhibit C is dated September 16, 2004. Exhibit D is dated October 19, 2004.

5. The present application docket no. 97-1433 (serial no. 09/266,237) is contained on page 6 of the docket records.

Exhibit A dated June 1, 2004 includes the entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Amendment 4/26/04".

Exhibit B dated July 21, 2004 includes the entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Amendment 4/26/04".

Exhibit C dated September 16, 2004 includes the hand written entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Issue Fee Transmittal + Petition 10/11/04".

Exhibit D dated October 19, 2004 includes the entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Issue Fee Transmittal and Petition" 10/11/04.

6. These docket records indicate that the Notice of Allowance And Fees Due mailed on 06/08/2004 for docket no. 97-1433 (serial no. 09/266,237) was not received by Attorney for Applicant in the time period for response of (06/08/2004 to 09/08/2004).

In view of the foregoing Applicant requests that the holding of abandonment be withdrawn. In addition, Applicant requests that the "Part B-Fee(s) Transmittal", the "Fee Address Indication Form" and the issue fee be accepted and processed.

Respectfully submitted:



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STEPHEN A. GRATTON  
Registration No. 28,418  
Attorney for Applicant

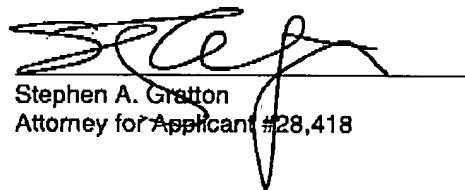
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CERTIFICATE OF TRANSMISSION UNDER 37 C.F.R. §1.8

I hereby certify that this correspondence entitled "Supplement to Petition To Accept Late Payment Of Issue Fee" (pages 1-4 and Exhibits A-D) is being facsimile transmitted to the United States Patent and Trademark Office on 03/02/2005 to Fax no. (571) 273-0025 for the Office of Petitions.

March 2, 2005

Date of Signature

  
Stephen A. Gratton  
Attorney for Applicant #28,418

## KG'DOCKET

## EXHIBIT A

CASE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman	Filed Amendment 4/26/04.
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433	Filed Amendment & IDS 4/30/04.
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433	Awaiting OA.
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311	Paid Issue Fee by 3/22/04.
99-311.2	Test Interconnect For Bumped Components (Method of Fab)	7/18/02	Div of 99-0311	Paid Issue Fee 2/13/04.
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2	<i>Spurious Cont'd 7/18/04</i> Awaiting OA.
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1	<i>Respond to OA by 6/4/04</i> Awaiting OA.
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1	Respond to OA by 2/18/04.*
99-068.2 09/653,166	Polymer Support Member For BGA (Method)	9/1/00	Warren, Alan Cont of 99-068.1	Paid Issue Fee 3/31/04.
99-068.3 10/693,380	Polymer Support Member For BGA (Method)	10/24/03	Warren, Alan Cont of 99-068.2	Updated IDS 2/6/04.
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703	Respond to OA by 8/10/04.*
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03		Awaiting OA.
99-0812.2 10/659,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1	Awaiting OA. <i>Respond to OA by 9/17/04</i> Updated IDS 11/11/03.

THE LAW OFFICE  
OF STEVE GRATTON

June 1, 2004

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**EXHIBIT C****INVENTION**

FILE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman Filed Amendment 4/26/04 Simpler Test of Thomas 9/16/04	
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433 Filed Respond 7/23/04.	
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433 Awaiting OA.	
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311 Paid Issue Fee by 3/22/04.	
99-311.2	Test Interconnect For Bumped Components	7/18/02	Div of 99-0311 Paid Issue Fee 2/13/04. Status Letter filed 7/21/04.	
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2 Awaiting OA.	
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1 Filed Amendment 6/22/04.	
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1 Paid Issue Fee 8/23/04.	
99-068.3 10/693,380	Polymer Support Member for BGA (Method)	10/24/03	Warren, Alan Cont of 99-0068.2 Updated IDS 2/6/04.	
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703 Filed Amendment & IDS 8/27/04.	
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03	Awaiting OA.	
99-0812.2 10/653,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1 Filed Amendment & IDS 9/17/04.	*Response due

## EXHIBIT B

## KGD DOCKET

CASE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman	Filed Amendment 4/26/04.
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433	Filed Amendment & IDS 4/30/04. <i>File Response 7/23/04</i>
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433	Awaiting OA.
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311	Paid Issue Fee by 3/22/04.
99-311.2	Test Interconnect for Bumped Components	7/18/02	Div of 99-0311	Paid Issue Fee 2/13/04. Status Letter Filed 7/21/04.
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2	Awaiting OA.
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1	Filed Amendment 6/22/04.
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1	FILED-REB-17157047
99-068.3 10/693,380	Polymer Support Member for BGA (Method)	10/24/03	Warren, Alan Cont of 99-0068.2	Update IDS 2/6/04. <i>AND File for 8/13/04</i>
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703	Respond to OA by 8/10/04.
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03		<i>File Response + IDS 8/14/04</i> Awaiting OA.
99-0812.2 10/659,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1	Respond to OA by 9/17/04.*

\*Response due

**EXHIBIT D****KGD DOCKET**

CASE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman Div of 97-1433	Filed Issue Fee Transmittal and Petition 10/11/04.
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433	Filed Response 7/23/04.
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433	Awaiting OA.
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311	Paid Issue Fee 3/22/04.
99-311.2	Test Interconnect for Bumped Components (Method of Fab)	7/18/02	Div of 99-0311	Paid Issue Fee 2/13/04. Status Letter filed 7/21/04.
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2	Awaiting OA.
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1	Filed Amendment 6/22/04.
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1	Paid Issue Fee 8/23/04.
99-068.3 10/693,380	Polymer Support Member for BGA (Method)	10/24/03	Warren, Alan Cont of 99-0068.2	Updated IDS 2/6/04.
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703	Filed Amendment & IDS 8/27/04. <i>Respond to FOIA by 2/10/05</i>
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03		Awaiting OA.
99-0812.2 10/659,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1	Filed Amendment & IDS 9/17/04.

\*Response due

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October 19, 2004

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